

ABSTRACT

The present invention relates to a substrate processing method and a substrate processing apparatus for processing a substrate, such as a wafer. In the substrate processing method, rollers (11a, 11b) secured to eccentric shafts (13a, 13b) including a reference shaft (13a) and a movable shaft (13b) are brought into contact with the periphery of a substrate (W) having a notch (Nw), and further the rollers (11a, 11b) are moved in a circular motion, thereby rotating and circularly moving the substrate (W), and further, processing the substrate (W) by bringing a processing tool (201) into contact with the substrate (W). During processing of the substrate (W), a rotational speed of the substrate (W) is calculated based on measured values of a notch detection sensor (77) which is capable of detecting that the notch (Nw) has passed the movable shaft (13b), and an alarm is issued when the rotational speed of the substrate (W) is out of an allowable range which is set with respect to a theoretical rotational speed of the substrate (W).

FIG. 2